

opportunity artnership

NASA Langley's

LaRC-SI

High-performance/high-temperature resins for dielectric films, coatings, composites, adhesives, and solid parts

imide (SI) during an advanced aeronautics materials research program. Langley found that this high temperature material has surprisingly good processing properties along with good machinability, solution casting, compression molding, and extrusion characteristics. LaRC-SI was quickly commercialized and has found its way into many applications, such as flexible and multilayer circuit substrates, dielectric film, wire insulation, mechanical parts, hot melt adhesive film, composites and fiber optic cladding. Becuase LaRC-SI is processed so easily by so many standard methods, the variety of applications that have not yet been explored far exceed those that have.

dielectric properties, and biological inertness



Applications

The technology offers wide-ranging market applications, including:

- Matrix resin for composites (carbon fiber and glass)
- Electronic packaging components
- · Optical cladding
- Dielectric coatings and films
- Structural or mechanical parts, either filled or unfilled
- High-temperature adhesives, coatings, and barriers
- · Radiation shielding
- Flame-retardant foam (structural and flexible)
- Low pressure bonding for sandwich panel construction

The Technology

LaRC-SI is a wholly aromatic high-performance thermoplastic polyimide that is a self-bonding/non-curing resin made from commercially available monomers. This polyimide has superior mechanical, electrical, and adhesive properties and an extensive range of processing choices that allow it to serve as either a dielectric inner layer, substrate coating, or the substrate. LaRC-SI film is made by casting or spraying a solution consisting of xylene, N-methyl-pyrrolidinone (NMP), and LaRC-SI powder. At different drying temperatures, various amounts of solvent are removed to the point where it becomes insoluble but retains its melt processability. LaRC-SI excels in the following characteristics:

- Solubility in conventional high-boiling solvents
- Melt flow and bonding properties
- Electrical properties low dissipation factor and high dielectric strength
- Resistance to harsh environments such as radiation, cryogenic and elevated temperatures, most fluids, corrosives, and biological inertness

Relevant base patents:

US Pat. 5,639,850 US Pat. 5,741,883 US Pat. 6,048,959

For More Information

If your company is interested in licensing or joint development opportunities associated with this technology, or if you would like additional information on partnering with NASA, please contact:

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